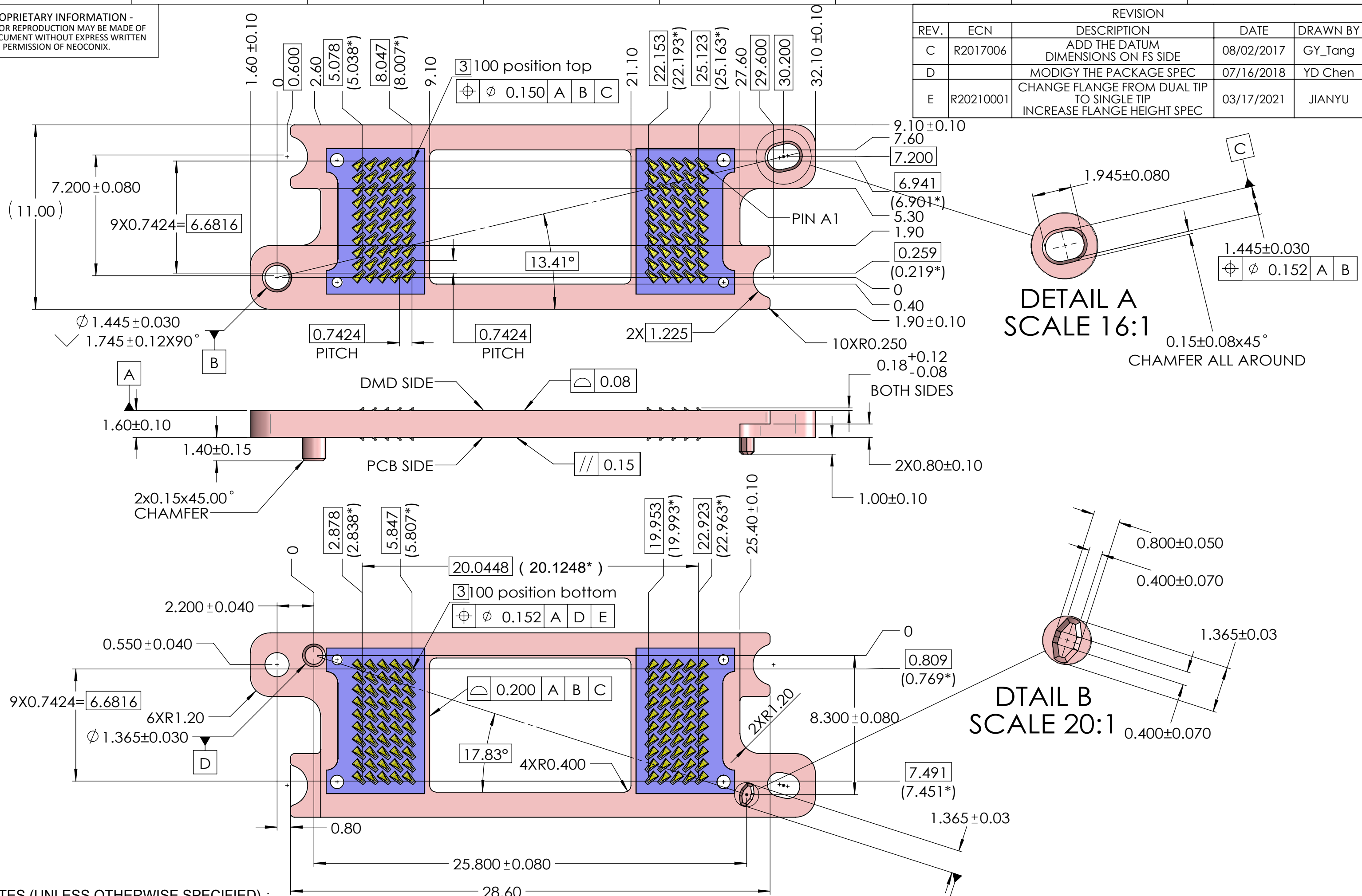


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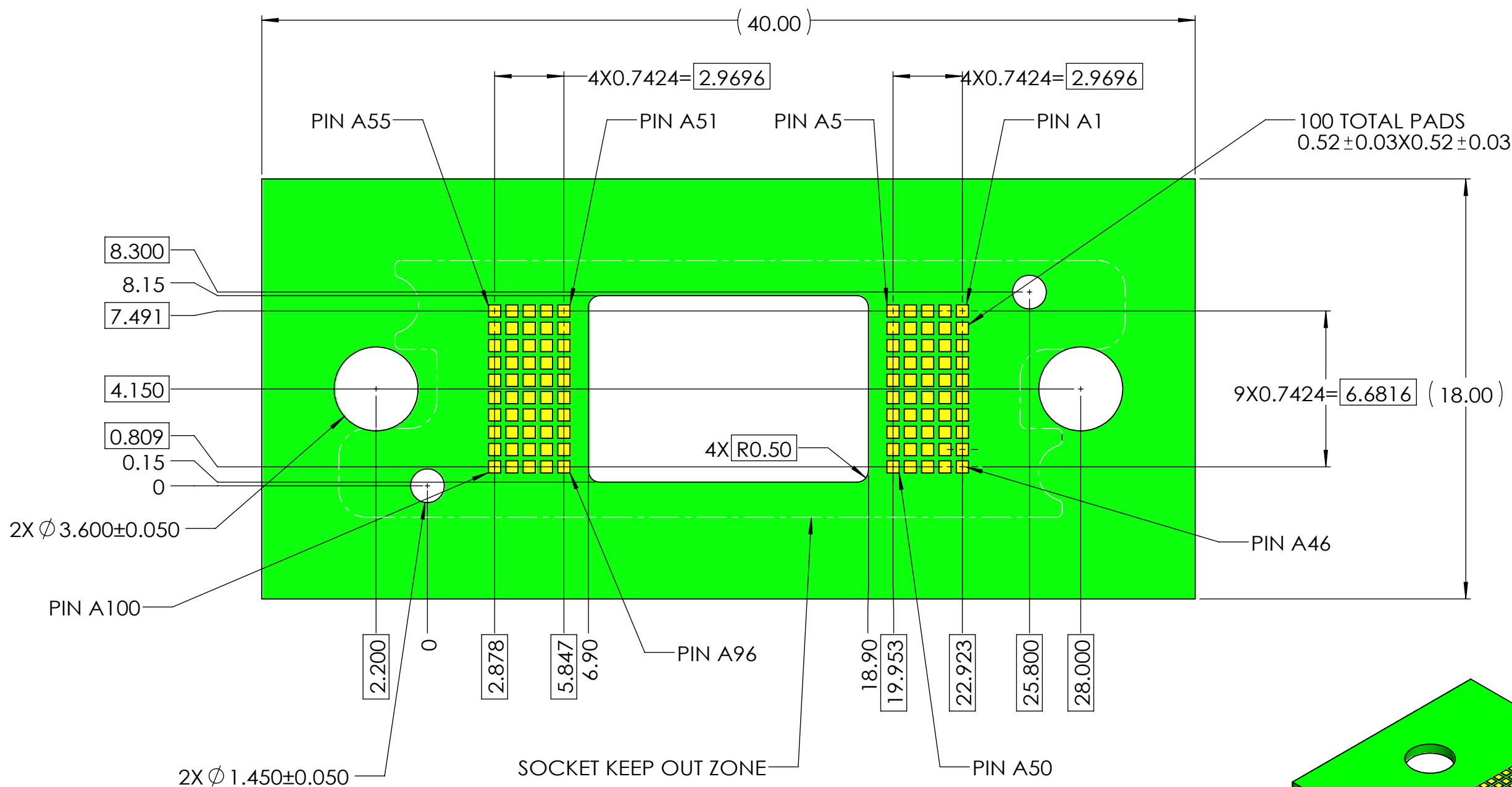
REVISION				
REV.	ECN	DESCRIPTION	DATE	DRAWN BY
C	R2017006	ADD THE DATUM DIMENSIONS ON FS SIDE	08/02/2017	GY_Tang
D		MODIFY THE PACKAGE SPEC	07/16/2018	YD Chen
E	R20210001	CHANGE FLANGE FROM DUAL TIP TO SINGLE TIP INCREASE FLANGE HEIGHT SPEC	03/17/2021	JIANYU



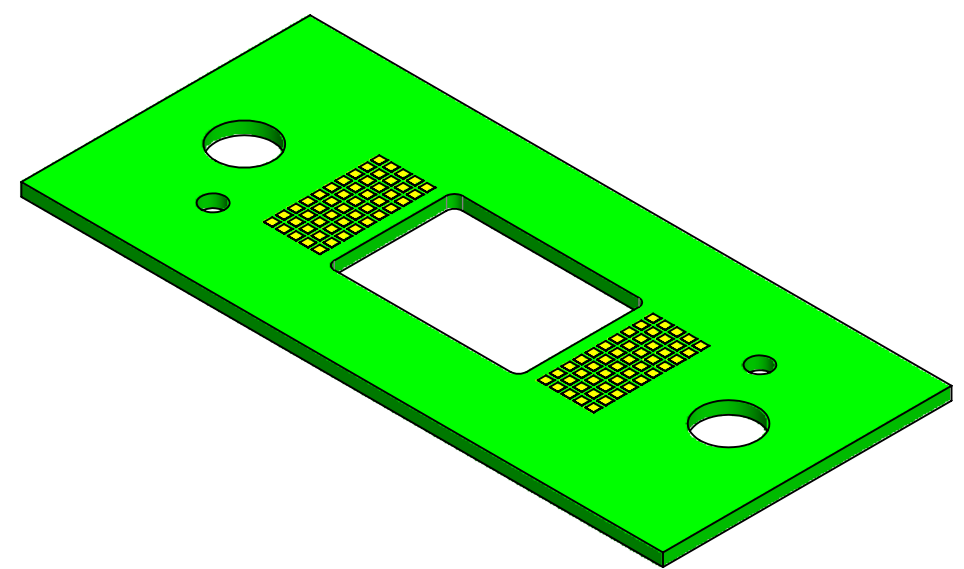
- NOTES (UNLESS OTHERWISE SPECIFIED):
1. INTERPRET DRAWING PER ASME Y14.5-94.
 2. COMPLIANT WITH RoHS DIRECTIVE 2011/65/EU.
 3. CENTER MARKS OF CONTACT POSITIONS ARE FOR COMPRESSED STATE.
* STAR MARKS OF CONTACT POSITIONS ARE FOR UNCOMPRESSED CONDITION.
 4. Material:
Contacts: High performance copper alloy.
Contact base: FR4 with plated through holes
Housing: LCP resin, Glass fiber filled, UL 94V-0 rated
Black color
Plating: 5 U" min gold plated on contact tip, 70±30 U" nickel underplated
 5. Either of the redundant contact tips can apply toward the true position location

<p>4020 Moorpark Ave, #108 San Jose, CA 95117 TEL: 408-530-9393 FAX: 408-530-9383</p>	<p>DIMENSIONS ARE IN MM [INCH] .X ± 0.13 [0.005] .XX ± 0.08 [0.003] .XXX ± 0.025 [0.001] ANGLE: NO DEC ± 1° .X ± 0.5° .XX ± 0.25°</p>	<p>MATERIAL: SEE NOTES FINISH: SEE NOTES</p>	<p>TITLE: 0.7424mm PITCH LGA-LGA 100 POS INTERPOSER(DMD 312)</p>
	<p>DRAWN BY: Jianyuzhang 2021/3/19 CHECKED BY: Gary Hsieh 2021/3/19 ENGR APPR: Gary Hsieh 2021/3/19 MFG APPR: QA APPR:</p>	<p>SIZE: B+ DWG NUMBER: BDX0100CMMHFAU00 SCALE: 10:1</p>	<p>REV: E SHEET 1 OF 3</p>

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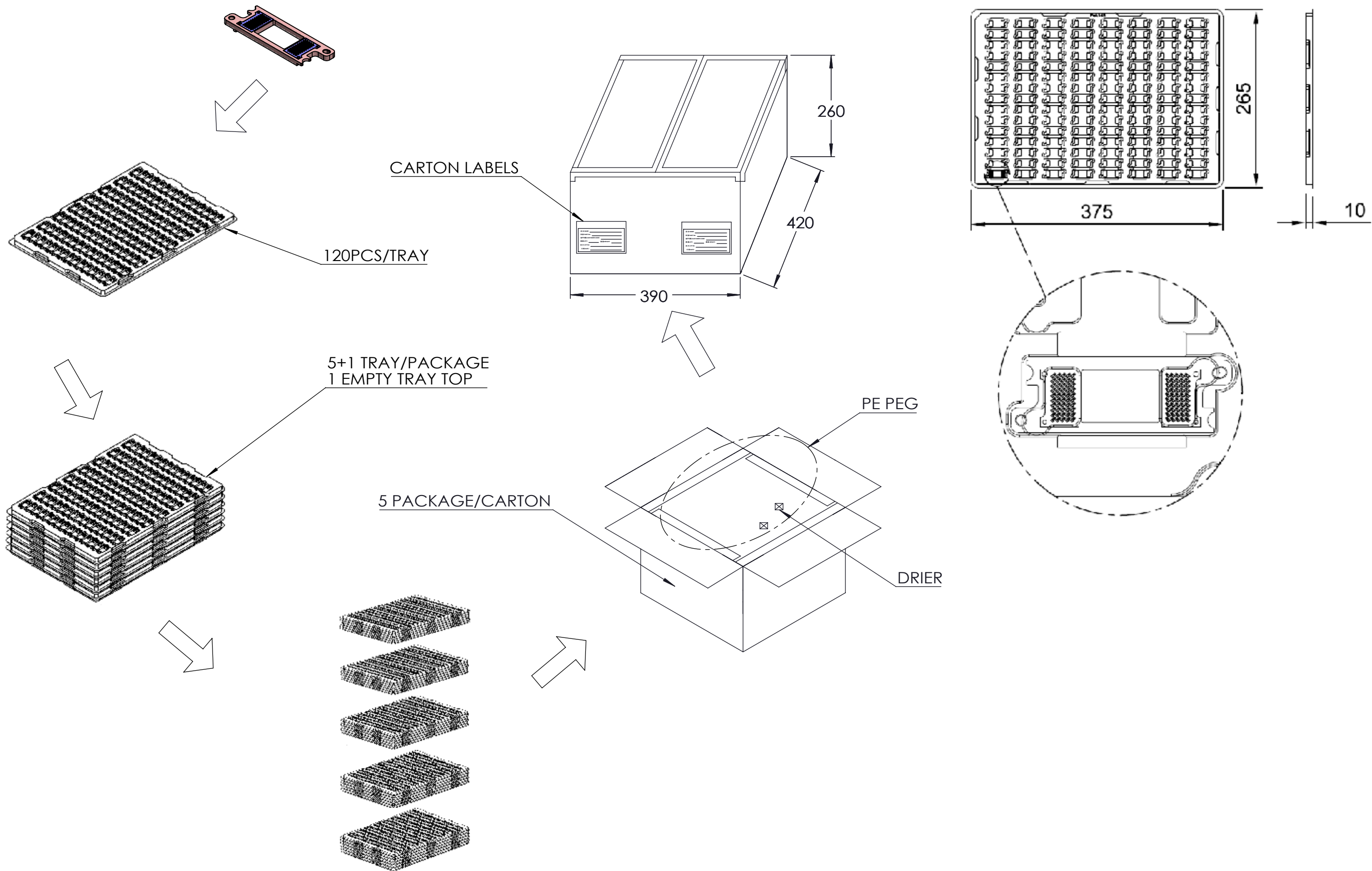
recommend PCB footprint



- NOTES: UNLESS OTHERWISE SPECIFIED:
- 1 PADS TO BE ELECTROLESS NICKEL / IMMERSION GOLD (ENIG) PLATED
 - 2 VIAS IN PAD AREAS MUST BE FILLED
 - 3 INTERPOSER OUTLINE; NO COMPONENTS ALLOWED WITHIN THIS AREA
 - 4 ALLOWED COMPONENT AREA; MAXIMUM COMPONENT HEIGHT 1.3 mm
 - 5 IF SOLDERMASK IS APPLIED IN THE ARRAY AREA.IT SHALL NOT PROTRUDE ABOVE THE PLANE OF THE CONTACT PAD SURFACE

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	DRAWN BY: Jianyuzhang 2021/3/19		CHECKED BY: Gary Hsieh 2021/3/19		SIZE: B+	
	ENGR APPR: Gary Hsieh 2021/3/19		MFG APPR:		DWG NUMBER: BDX0100CMMHFAU00	
	QA APPR:		SCALE: 10:1		SHEET 2 OF 3	

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NOTE(UNLESS OTHERWISH SPECIFIED):
1.COMPONENT LOAD PER TRAY : 120PCS
5 TRAY/PACKAGE:600 PCS
5 PACKAGE/CARTON: 420mm X 390mm X 260mm.
TOTAL: 3000PCS/CARTON
2.MATERIAL:TRANSPARENT POLYSTYRENE(PS).

<p>4020 Moorpark Ave, #108 San Jose, CA 95117 TEL: 408-530-9393 FAX: 408-530-9383</p>	DIMENSIONS ARE IN MM [INCH]		MATERIAL: SEE NOTES		TITLE: PACKAGE SPEC	
	.X ± 0.13 [.005]	✓	FINISH: --		SIZE B+	DWG NUMBER: BDX0100CMMHFAU00
	.XX ± 0.08 [.003]		DRAWN BY: Jianyuzhang 2021/3/19			
	.XXX ± 0.04 [.001]		CHECKED BY: Jason Wu 2021/3/19		ENGR APPR: Gary Hsieh 2021/3/19	
ANGLE: NO DEC ± 1° .X ± 0.5° .XX ± 0.25°		MFG APPR:		QA APPR:		
				SCALE: 2:1 SHEET 3 OF 3		